



Creative Materials, Inc.
12 Willow Road
Ayer, MA 01432

T 978.391.4700
F 978.391.4705

111-17

ONE COMPONENT EPOXY POTTING COMPOUND

DESCRIPTION: 111-17 is a medium viscosity, one component, low stress, low shrink-potting compound. 111-17 features *exceptional* resistance to thermal cycling. Recommended applications include potting and bonding of dissimilar materials requiring Class "H" (180°C) service temperature rating. 111-17 can also be used as an adhesive for bonding stress sensitive substrates.

TYPICAL CURED PROPERTIES:

Specific Gravity	1.56
Hardness (Shore D)	> 85
Coef. of Therm. Exp. (in/in/°C x 10 ⁻⁶)	21
Therm. Cond. (W/mK)	0.85
Cure Shrinkage (%)	0.187
Fungus Resistance	Non-nutrient
Tensile Strength (psi)	9600
Water Absorption (%)	< 0.19
Dielectric Strength (volts/mil)	475
Volume Resistivity (Ω-cm)	2.1 x 10 ¹⁵
Power Factor (60 HZ)	0.028
Dielectric Constant	4.3 @ 60 HZ

HANDLING & CURING INSTRUCTIONS: Material is ready to use as received. Store at low temperature to maintain consistent flow properties. Allow material to warm up to room temperature before opening container. Cure for 2 to 3 hours at 121°C. Alternate cure schedule is 30 minutes at 160°C, or 10 to 15 minutes at 177°C.

STORAGE: Shelf Life: 12 months at -18°C; or 2 months at 4°C; or 1 month at 25°C.

SAFETY & HANDLING: Use with adequate ventilation. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin. In case of eye contact, flush immediately with water and secure medical attention.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 2/10/09 REVISION: A